9-11-1987

UD Hosts Engineering Seminar

Follow this and additional works at: https://ecommons.udayton.edu/news_rls

Recommended Citation
https://ecommons.udayton.edu/news_rls/4808

This News Article is brought to you for free and open access by the Marketing and Communications at eCommons. It has been accepted for inclusion in News Releases by an authorized administrator of eCommons. For more information, please contact frice1@udayton.edu, mschlangen1@udayton.edu.
DAYTON, Ohio, September 11, 1987--As electronic circuits become smaller and more complex, the packaging that holds the circuits is becoming obsolete. The Institute of Electrical and Electronic Engineers, Inc. (IEEE), an international professional society, will address that problem in "High Performance Integrated Circuit Packaging," a live seminar to be held at the University of Dayton Tuesday, September 22.

Presenters are Barry Johnson and Douglas Hamilton, both from the University of Arizona; Mali Mahalingam of Motorola; and Glenn Shirley of Intel.

The seminar, which is open to the public, will run from 10:30 a.m. to 4 p.m. in Kennedy Union on the UD campus.

The registration fee of $75 ($50 for IEEE members) includes all seminar materials and refreshments. Registration by Tuesday, September 15, is recommended.

To register or for more information, call UD's Continuing Education at 229-2347.